









Release Date: 08 September 2022 Version: A1.0

PRODUCT DATASHEET



- ► Ceramic High Power
- ➤ 2016 0.78t Series
- ► IR (930~950nm)

N0F62S43



2016 0.78t Series





FEATURES:

Package: Ceramic IR CHIP SMT Package

Forward Current: 9mA

Forward Voltage (typ.): 1.9V

Radiant Power (typ.): 5mW@9mA

Colour: Infrared (IR)

Peak Wavelength: 930-950nm

Viewing angle: 120°

Materials:

L/F: Ceramic

Operating Temperature: -20~+65°C

Storage Temperature: -20~+65°C

Grouping parameters:

Forward Voltage

Radiant Power

Peak Wavelength

Soldering methods: IR Reflow soldering

MSL: Level 3 according to J-STD020

Packing: 8mm tape with max.1000pcs/reel, ø178mm (7")

2016 0.78t Series

APPLICATIONS:

- Security Camera
- Medical Device
- Fluorochemistry
- **Bacterial Identification** Cosmetology
- Magnetic Particle Inspection
- Clean Room Inspection
- Mineralogy



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

| Parameter | Symbol | Ratings | Unit |
|---|------------------|---------|------|
| DC Forward Current | I _F | 9 | mA |
| Reverse Voltage | V _R | 5 | V |
| Leakage Current @5V | I _R | 10 | μΑ |
| Junction Temperature | Tj | 115 | °C |
| Thermal Resistance Junction to Solder Point | R_{thj-sp} | 133 | °C/W |
| Operating Temperature | TOPR | -20~+65 | °C |
| Storage Temperature | T _{STG} | -20~+65 | °C |

Electrical & Optical Characteristics (Ta=25°C)

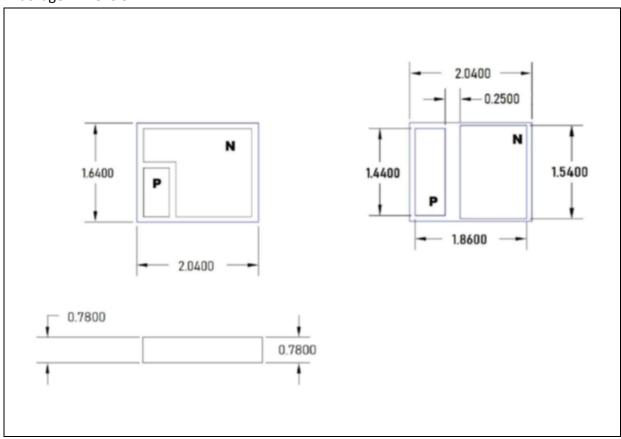
| Parameter | Symbol | Values | | | Unit | Test |
|--------------------------------|-------------------|--------|------|------|-------|---------------------|
| Parameter | | Min. | Тур. | Max. | Onit | Condition |
| Operation Voltage | V _F | 1.7 | 1.9 | 2.2 | V | I _F =9mA |
| Threshold Current | I _{th} | | 2 | | mA | |
| Output Power | Po | 4 | 5 | | mW | I _F =9mA |
| Slope Efficiency | ŋs | 0.5 | 0.7 | | mW/mA | I _F =9mA |
| Power Conversion Efficiency | φр | | 35 | | % | I _F =9mA |
| Peak Wavelength | W _P | 930 | 940 | 950 | nm | I _F =9mA |
| Viewing Angle | 2θ _{1/2} | | 120 | | deg | I _F =9mA |
| Far Field Angle | θ | | 20 | | deg | I _F =9mA |

^{1.} Radiant Power (P_0) $\pm 10\%$, Forward Voltage (V_F) $\pm 0.05V$, Wavelength (nm) ± 2 nm



OUTLINE DIMENSION:

Package Dimension:

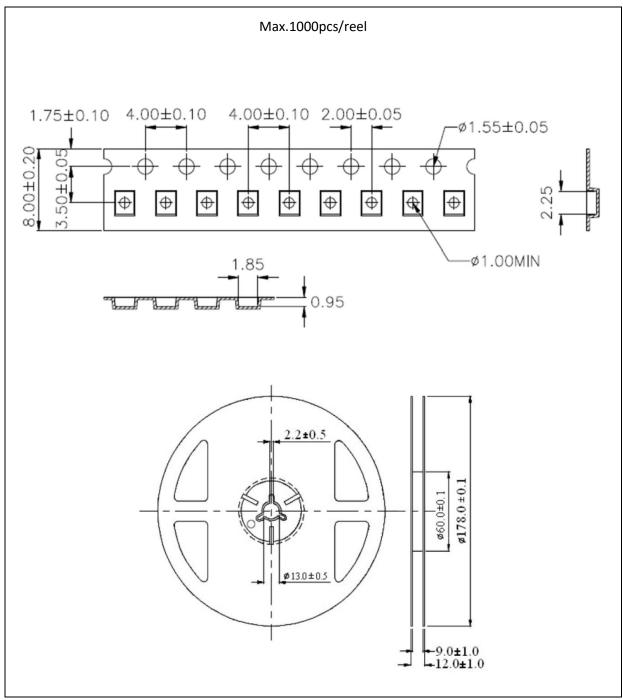


- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

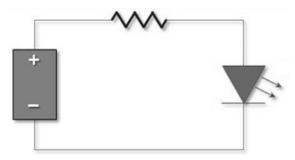
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 65±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

| Version | Date | Summary of Revision |
|---------|------------|---------------------|
| A1.0 | 08/09/2022 | Datasheet set-up. |